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TAPIA KRISTA

Advances in Chemical Mechanical Planarization (CMP)
CRC Press

"This text follows the tradition of Sze's highly successful pioneering text on VLSI technology and is updated with the latest advances in the field of microelectronic chip fabrication. Since computer chips are foundations of modern electronics, these topics are essential for the next generation of USLI technologies, allowing more transistors to be packaged on a single chip. Contributing to each chapter are industry experts, specializing in topics such as epitaxy with low temperature process, rapid thermal processes, low damage plasma reactive ion etching, fine line litography, cleaning technology, clean room technology, packing and reliability."--

Introduction to Microelectronic Fabrication Academic Press

In this book, a variety of topics related to Very-Large-Scale Integration (VLSI) is extensively discussed. The topics encompass the physics of VLSI transistors, the process of integrated chip design and fabrication and the applications of VLSI devices. It is intended to provide information on the latest advancement of VLSI technology to researchers, physicists as well as engineers working in the field of semiconductor manufacturing and VLSI design.

MEMS and NEMS World Scientific

The performance of high-speed semiconductor devices—the genius driving digital computers, advanced electronic systems for digital signal processing, telecommunication systems, and optoelectronics—is inextricably linked to the unique physical and electrical properties of gallium arsenide. Once viewed as a novel alternative to silicon, gallium arsenide has swiftly moved into the forefront of the leading high-tech industries as an irreplaceable material in component fabrication. GaAs High-Speed Devices provides a comprehensive, state-of-the-science look at the phenomenally expansive range of engineering devices gallium arsenide has made possible—as well as the fabrication methods, operating principles, device models, novel device designs, and the material properties and physics of GaAs that are so keenly integral to their success. In a clear five-part format, the book systematically examines each of these aspects of GaAs device technology, forming the first authoritative study to consider so many important aspects at once and in such detail. Beginning with chapter 2 of part one, the book discusses such basic subjects as gallium arsenide materials and crystal properties, electron energy band structures, hole and electron transport, crystal growth of GaAs from the melt and defect density analysis. Part two describes the fabrication process of gallium arsenide devices and integrated circuits, shedding light, in chapter 3, on epitaxial growth processes, molecular beam epitaxy, and metal organic chemical vapor deposition techniques. Chapter 4 provides an introduction to wafer cleaning techniques and environment control, wet etching methods and chemicals, and dry etching systems, including reactive ion etching, focused ion beam, and laser assisted methods. Chapter 5 provides a clear overview of photolithography and

nonoptical lithography techniques that include electron beam, x-ray, and ion beam lithography systems. The advances in fabrication techniques described in previous chapters necessitate an examination of low-dimension device physics, which is carried on in detail in chapter 6 of part three. Part four includes a discussion of innovative device design and operating principles which deepens and elaborates the ideas introduced in chapter 1. Key areas such as metal-semiconductor contact systems, Schottky Barrier and ohmic contact formation and reliability studies are examined in chapter 7. A detailed discussion of metal semiconductor field-effect transistors, the fabrication technology, and models and parameter extraction for device analyses occurs in chapter 8. The fifth part of the book progresses to an up-to-date discussion of heterostructure field-effect (HEMT in chapter 9), potential-effect (HBT in chapter 10), and quantum-effect devices (chapters 11 and 12), all of which are certain to have a major impact on high-speed integrated circuits and optoelectronic integrated circuit (OEIC) applications. Every facet of GaAs device technology is placed firmly in a historical context, allowing readers to see instantly the significant developmental changes that have shaped it. Featuring a look at devices still under development and device structures not yet found in the literature, GaAs High-Speed Devices also provides a valuable glimpse into the newest innovations at the center of the latest GaAs technology. An essential text for electrical engineers, materials scientists, physicists, and students, GaAs High-Speed Devices offers the first comprehensive and up-to-date look at these formidable 21st century tools. The unique physical and electrical properties of gallium arsenide has revolutionized the hardware essential to digital computers, advanced electronic systems for digital signal processing, telecommunication systems, and optoelectronics. GaAs High-Speed Devices provides the first fully comprehensive look at the enormous range of engineering devices gallium arsenide has made possible as well as the backbone of the technology—ication methods, operating principles, and the materials properties and physics of GaAs—device models and novel device designs. Featuring a clear, six-part format, the book covers: GaAs materials and crystal properties Fabrication processes of GaAs devices and integrated circuits Electron beam, x-ray, and ion beam lithography systems Metal-semiconductor contact systems Heterostructure field-effect, potential-effect, and quantum-effect devices GaAs Microwave Monolithic Integrated Circuits and Digital Integrated Circuits In addition, this comprehensive volume places every facet of the technology in an historical context and gives readers an unusual glimpse at devices still under development and device structures not yet found in the literature.

VLSI Technology CRC Press

The development of micro- and nano-mechanical systems (MEMS and NEMS) foreshadows momentous changes not only in the technological world, but in virtually every aspect of human life. The future of the field is bright with

opportunities, but also riddled with challenges, ranging from further theoretical development through advances in fabrication technologies, to developing high-performance nano- and microscale systems, devices, and structures, including transducers, switches, logic gates, actuators and sensors. MEMS and NEMS: Systems, Devices, and Structures is designed to help you meet those challenges and solve fundamental, experimental, and applied problems. Written from a multi-disciplinary perspective, this book forms the basis for the synthesis, modeling, analysis, simulation, control, prototyping, and fabrication of MEMS and NEMS. The author brings together the various paradigms, methods, and technologies associated with MEMS and NEMS to show how to synthesize, analyze, design, and fabricate them. Focusing on the basics, he illustrates the development of NEMS and MEMS architectures, physical representations, structural synthesis, and optimization. The applications of MEMS and NEMS in areas such as biotechnology, medicine, avionics, transportation, and defense are virtually limitless. This book helps prepare you to take advantage of their inherent opportunities and effectively solve problems related to their configurations, systems integration, and control.

VLSI Fabrication Principles Elsevier

Learn the basic properties and designs of modern VLSI devices, as well as the factors affecting performance, with this thoroughly updated second edition. The first edition has been widely adopted as a standard textbook in microelectronics in many major US universities and worldwide. The internationally renowned authors highlight the intricate interdependencies and subtle trade-offs between various practically important device parameters, and provide an in-depth discussion of device scaling and scaling limits of CMOS and bipolar devices. Equations and parameters provided are checked continuously against the reality of silicon data, making the book equally useful in practical transistor design and in the classroom. Every chapter has been updated to include the latest developments, such as MOSFET scale length theory, high-field transport model and SiGe-base bipolar devices.

Electronic Materials John Wiley & Sons

The fourth edition of CMOS Digital Integrated Circuits: Analysis and Design continues the well-established tradition of the earlier editions by offering the most comprehensive coverage of digital CMOS circuit design, as well as addressing state-of-the-art technology issues highlighted by the widespread use of nanometer-scale CMOS technologies. In this latest edition, virtually all chapters have been re-written, the transistor model equations and device parameters have been revised to reflect the sigificant changes that must be taken into account for new technology generations, and the material has been reinforced with up-to-date examples. The broad-ranging coverage of this textbook starts with the fundamentals of CMOS process technology, and continues with MOS transistor models, basic CMOS gates, interconnect effects, dynamic circuits, memory circuits, arithmetic building blocks,

clock and I/O circuits, low power design techniques, design for manufacturability and design for testability.
Microsystem Technology Springer Science & Business Media
MEMS technology and applications have grown at a tremendous pace, while structural dimensions have grown smaller and smaller, reaching down even to the molecular level. With this movement have come new types of applications and rapid advances in the technologies and techniques needed to fabricate the increasingly miniature devices that are literally changing our world. A bestseller in its first edition, Fundamentals of Microfabrication, Second Edition reflects the many developments in methods, materials, and applications that have emerged recently. Renowned author Marc Madou has added exercise sets to each chapter, thus answering the need for a textbook in this field. Fundamentals of Microfabrication, Second Edition offers unique, in-depth coverage of the science of miniaturization, its methods, and materials. From the fundamentals of lithography through bonding and packaging to quantum structures and molecular engineering, it provides the background, tools, and directions you need to confidently choose fabrication methods and materials for a particular miniaturization problem. New in the Second Edition Revised chapters that reflect the many recent advances in the field Updated and enhanced discussions of topics including DNA arrays, microfluidics, micromolding techniques, and nanotechnology In-depth coverage of bio-MEMs, RF-MEMs, high-temperature, and optical MEMs. Many more links to the Web Problem sets in each chapter
VLSI in Medicine John Wiley & Sons
VLSI Electronics Microstructure Science, Volume 17: VLSI in Medicine deals with the more important applications of VLSI in medical devices and instruments. This volume is comprised of 11 chapters. It begins with an article about medical electronics. The following three chapters cover diagnostic imaging, focusing on such medical devices as magnetic resonance imaging, neurometric analyzer, and ultrasound. Chapters 5, 6, and 7 present the impact of VLSI in cardiology. The electrocardiograph, implantable cardiac pacemaker, and the use of VLSI in Holter monitoring are detailed in these chapters. The neurostimulator is described in Chapter 8. Chapter 9 discusses both implantable and external drug infusion pumps and describes the use of VLSI in a particular external pump. The last two chapters cover topics that apply to the entire field of medical electronics. Engineers, scientists, medical practitioners and researchers will find the book very useful.
Flying Buttresses, Entropy, and O-rings ASTM International
VLSI Electronics Microstructure Science, Volume 15: VLSI Metallization discusses the various issues and problems related to VLSI metallization. It details the available solutions and presents emerging trends. This volume is comprised of 10 chapters. The two introductory chapters, Chapter 1 and 2 serve as general references for the electrical and metallurgical properties of

thin conducting films. Subsequent chapters review the various aspects of VLSI metallization. The order of presentation has been chosen to follow the common processing sequence. In Chapter 3, some relevant metal deposition techniques are discussed. Chapter 4 presents the methods of VLSI lithography and etching. Conducting films are first deposited at the gate definition step; therefore, the issues related to gate metallization are discussed next in Chapter 5.In Chapter 6, contact metallization is elaborated, and Chapter 7 is devoted to multilevel metallization schemes. Long-time reliability is the subject of Chapter 8, which discusses the issues of contact and interconnect electromigration. GaAs metallization is tackled in Chapter 9. The volume concludes with a general discussion of the functions of interconnect systems in VLSI. Materials scientists, processing and design engineers, and device physicists will find the book very useful.

SEMICONDUCTOR DEVICES: PHYSICS AND TECHNOLOGY, 2ND ED
Elsevier

Winner, 2013 PROSE Award, Engineering and Technology Concise, high quality and comparative overview of state-of-the-art electron device development, manufacturing technologies and applications Guide to State-of-the-Art Electron Devices marks the 60th anniversary of the IRE electron devices committee and the 35th anniversary of the IEEE Electron Devices Society, as such it defines the state-of-the-art of electron devices, as well as future directions across the entire field. Spans full range of electron device types such as photovoltaic devices, semiconductor manufacturing and VLSI technology and circuits, covered by IEEE Electron and Devices Society Contributed by internationally respected members of the electron devices community A timely desk reference with fully-integrated colour and a unique lay-out with sidebars to highlight the key terms Discusses the historical developments and speculates on future trends to give a more rounded picture of the topics covered A valuable resource R&D managers; engineers in the semiconductor industry; applied scientists; circuit designers; Masters students in power electronics; and members of the IEEE Electron Device Society.

Physics of Semiconductor Devices
Routledge

This is an up-to-date treatment of the analysis and design of CMOS integrated digital logic circuits. The self-contained book covers all of the important digital circuit design styles found in modern CMOS chips, emphasizing solving design problems using the various logic styles available in CMOS.

VLSI Metallization Wiley-Interscience

Improve your circuit-design potential with this expert guide to the devices and technology used in mixed analog-digital VLSI chips for such high-volume applications as hard-disk drives, wireless telephones, and consumer electronics. The book provides you with a critical understanding of device models, fabrication technology, and layout as they apply to mixed analog-digital circuits.You will learn about the many device-modeling requirements for analog work, as well as the

pitfalls in models used today for computer simulators such as Spice. Also included is information on fabrication technologies developed specifically for mixed-signal VLSI chips, plus guidance on the layout of mixed analog-digital chips for a high degree of analog-device matching and minimum digital-to-analog interference.This reference book features an intuitive introduction to MOSFET operation that will enable you to view with insight any MOSFET model ? besides thorough discussions on valuable large-signal and small-signal models.Filled with practical information, this first-of-its-kind book will help you grasp the nuances of mixed-signal VLSI-device models and layout that are crucial to the design of high-performance chips.
Insulated Gate Bipolar Transistor IGBT Theory and Design CRC Press
The new edition of the most detailed and comprehensive single-volume reference on major semiconductor devices The Fourth Edition of Physics of Semiconductor Devices remains the standard reference work on the fundamental physics and operational characteristics of all major bipolar, unipolar, special microwave, and optoelectronic devices. This fully updated and expanded edition includes approximately 1,000 references to original research papers and review articles, more than 650 high-quality technical illustrations, and over two dozen tables of material parameters. Divided into five parts, the text first provides a summary of semiconductor properties, covering energy band, carrier concentration, and transport properties. The second part surveys the basic building blocks of semiconductor devices, including p-n junctions, metal-semiconductor contacts, and metal-insulator-semiconductor (MIS) capacitors. Part III examines bipolar transistors, MOSFETs (MOS field-effect transistors), and other field-effect transistors such as JFETs (junction field-effect-transistors) and MESFETs (metal-semiconductor field-effect transistors). Part IV focuses on negative-resistance and power devices. The book concludes with coverage of photonic devices and sensors, including light-emitting diodes (LEDs), solar cells, and various photodetectors and semiconductor sensors. This classic volume, the standard textbook and reference in the field of semiconductor devices: Provides the practical foundation necessary for understanding the devices currently in use and evaluating the performance and limitations of future devices Offers completely updated and revised information that reflects advances in device concepts, performance, and application Features discussions of topics of contemporary interest, such as applications of photonic devices that convert optical energy to electric energy Includes numerous problem sets, real-world examples, tables, figures, and illustrations; several useful appendices; and a detailed solutions manual for Instructor's only Explores new work on leading-edge technologies such as MODFETs, resonant-tunneling diodes, quantum-cascade lasers, single-electron transistors, real-space-transfer devices, and MOS-controlled thyristors Physics of Semiconductor Devices, Fourth Edition is an indispensable resource for design engineers, research scientists,

industrial and electronics engineering managers, and graduate students in the field.

CMOS Digital Integrated Circuits Harvard University Press
This completely revised edition of a bestselling concise introduction to microsystems technology includes the latest trends in this emerging scientific discipline. The chapters on silicium and LIGA technology are greatly expanded, whilst new topics include application aspects in medicine and health technology, lithography and electroplating.

Semiconductor Devices, Physics and Technology Wiley-Interscience
Market_Desc: · Electrical Engineers· Scientists Special Features: · Provides strong coverage of all key semiconductor devices. Includes basic physics and material properties of key semiconductors· Covers all important processing technologies About The Book: This book is an introduction to the physical principles of modern semiconductor devices and their advanced fabrication technology. It begins with a brief historical review of major devices and key technologies and is then divided into three sections: semiconductor material properties, physics of semiconductor devices and processing technology to fabricate these semiconductor devices.

Semiconductor Sensors Springer Science & Business Media
Electronic materials are a dominant factor in many areas of modern technology. The need to understand'them is paramount; this book addresses that need. The main aim of this volume is to provide a broad unified view of electronic materials, including key aspects of their science and technology and also, in many cases, their commercial implications. It was considered important that much of the contents of such an overview should be intelligible by a broad audience of graduates and industrial scientists, and relevant to advanced undergraduate studies. It should also be up to date and even looking forward to the future. Although more extensive, and written specifically as a text, the resulting book has much in common with a short course of the same name given at Coventry Polytechnic. The interpretation of the term "electronic materials" used in this volume is a very broad one, in line with the initial aim. The principal restriction is that, with one or two minor exceptions relating to aspects of device processing, for example, the materials dealt with are all active materials. Materials such as simple insulators or simple conductors, playing only a passive role, are not singled out for consider ation. Active materials might be defined as those involved in the processing of signals in a way that depends crucially on some specific property of those materials, and the immediate question then concerns the types of signals that might be considered.

VLSI Technology John Wiley & Sons
This is a superb state-of-the-art collection of contributed readings by nationally recognized authorities in VLSI technology. The emphasis of this text is on fabrication.

Semiconductor Physical Electronics Woodhead Publishing
A practical guide to semiconductor manufacturing from processcontrol to yield modeling and

experimental design Fundamentals of Semiconductor Manufacturing and Process Controlcovers all issues involved in manufacturing microelectronic devicesand circuits, including fabrication sequences, process control,experimental design, process modeling, yield modeling, and CIM/CAMsystems. Readers are introduced to both the theory and practice ofall basic manufacturing concepts. Following an overview of manufacturing and technology, the textexplores process monitoring methods, including those that focus onproduct wafers and those that focus on the equipment used toproduce wafers. Next, the text sets forth some fundamentals ofstatistics and yield modeling, which set the foundation for adetailed discussion of how statistical process control is used toanalyze quality and improve yields. The discussion of statistical experimental design offers readers apowerful approach for systematically varying controllable processconditions and determining their impact on output parameters thatmeasure quality. The authors introduce process modeling concepts,including several advanced process control topics such asrun-by-run, supervisory control, and process and equipmentdiagnosis. Critical coverage includes the following: * Combines process control and semiconductor manufacturing * Unique treatment of system and software technology and managementof overall manufacturing systems * Chapters include case studies, sample problems, and suggestedexercises * Instructor support includes electronic copies of the figures andan instructor's manual Graduate-level students and industrial practitioners will benefitfrom the detailed exami?nation of how electronic materials andsupplies are converted into finished integrated circuits andelectronic products in a high-volume manufacturingenvironmen t. An Instructor's Manual presenting detailed solutions to all theproblems in the book is available from the Wiley editorialdepartment. An Instructor Support FTP site is also available.

CMOS Logic Circuit Design Springer Science & Business Media

'This is an excellent reference book for graduates or undergraduates studying semiconductor technology, or for working professionals who need a reference for detailed theory and working knowledge of processes in the field of power semiconductor devices.'IEEE Electrical Insulation MagazineThis descriptive textbook provides a clear look at the theories and process technologies necessary for understanding the modern power semiconductor devices, i.e. from the fundamentals of p-n junction electrostatics, unipolar MOSFET and superjunction structures, bipolar IGBT, to the most recent wide bandgap SiC and GaN devices. It also covers their associated semiconductor process technologies. Real examples based on actual fabricated devices, with the process steps described in clear detail are especially useful. This book is suitable for university courses on power semiconductor or power electronic devices. Device designers and researchers will also find this book a good reference in their work,

especially for those focusing on the advanced device development and design aspects.

Mixed Analog-digital VLSI Devices and Technology John Wiley & Sons

The summer school on VLSf GAD Tools and Applications was held from July 21 through August 1, 1986 at Beatenberg in the beautiful Bernese Oberland in Switzerland. The meeting was given under the auspices of IFIP WG 10. 6 VLSI, and it was sponsored by the Swiss Federal Institute of Technology Zurich, Switzerland. Eighty-one professionals were invited to participate in the summer school, including 18 lecturers. The 81 participants came from the following countries: Australia (1), Denmark (1), Federal Republic of Germany (12), France (3), Italy (4), Norway (1), South Korea (1), Sweden (5), United Kingdom (1), United States of America (13), and Switzerland (39). Our goal in the planning for the summer school was to introduce the audience into the realities of CAD tools and their applications to VLSI design. This book contains articles by all 18 invited speakers that lectured at the summer school. The reader should realize that it was not intended to publish a textbook. However, the chapters in this book are more or less self-contained treatments of the particular subjects. Chapters 1 and 2 give a broad introduction to VLSI Design. Simulation tools and their algorithmic foundations are treated in Chapters 3 to 5 and 17. Chapters 6 to 9 provide an excellent treatment of modern layout tools. The use of CAD tools and trends in the design of 32-bit microprocessors are the topics of Chapters 10 through 16. Important aspects in VLSI testing and testing strategies are given in Chapters 18 and 19.